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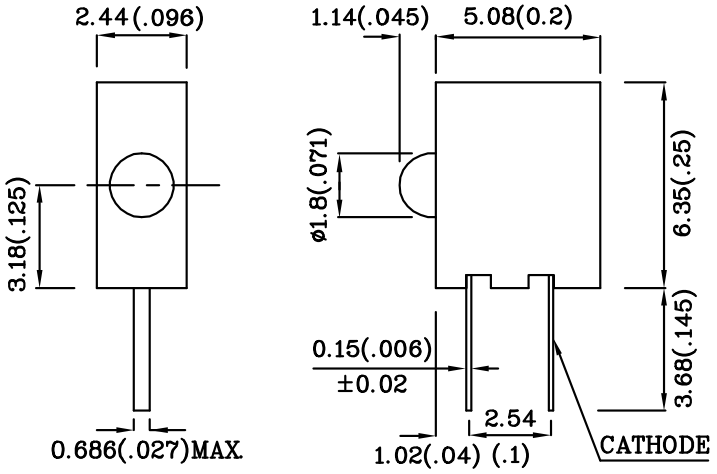
Part Number: **XNH1ZUR46D5V**

SUBMINIATURE SOLID STATE LAMP

Features

- BLACK CASE ENHANCES CONTRAST.
- VIBRATION AND SHOCK RESISTANT.
- UL RATING : 94V-0.
- HOUSING MATERIAL: TYPE 66 NYLON.
- 5V INTERNAL RESISTOR.
- RoHS COMPLIANT.



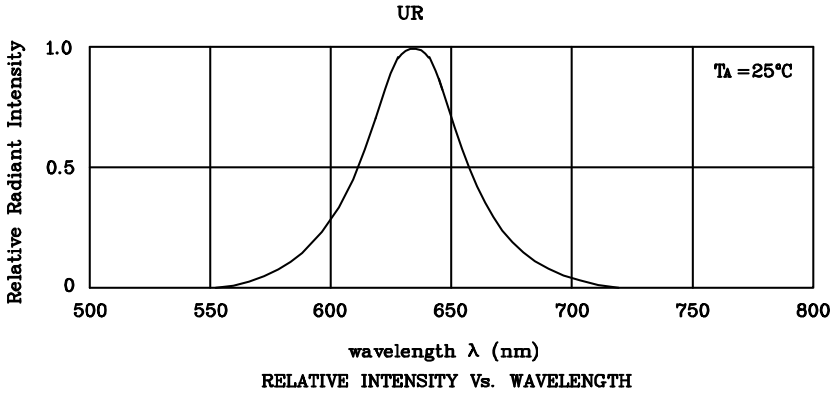
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

Absolute maximum ratings (T_A=25°C)		**UR (GaAsP/ GaP)**	**Unit**
Reverse Voltage	V_R	5	V
Forward Voltage	V_F	6	V
Power Dissipation	P_T	85	mW
Operating Temperature	T_A	-40 ~ +70	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

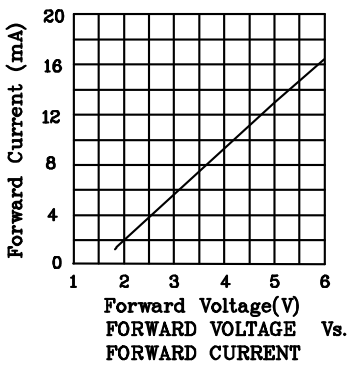
Operating Characteristics (T_A=25°C)		**UR (GaAsP/ GaP)**	**Unit**
Forward Current (Typ.) (V_F=5V)	I_F	13	mA
Forward Current (Max.) (V_F=5V)	I_F	17.5	mA
Reverse Current (V_R=5V)	I_R	10	uA
Wavelength of Peak Emission (V_F=5V)	λ P	627	nm
Wavelength of Dominant Emission (V_F=5V)	λ D	625	nm
Spectral Line Full Width At Half-Maximum (V_F=5V)	Δλ	45	nm

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (V =5V) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XNH1ZUR46D5V	Red	GaAsP/GaP	Red Diffused	1.8	7	627	40°

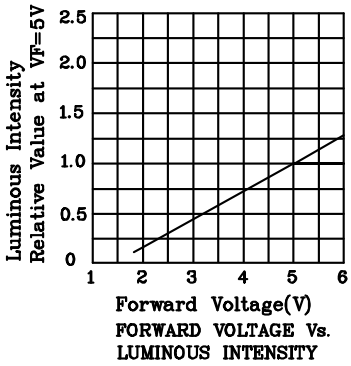


RELATIVE INTENSITY Vs. WAVELENGTH

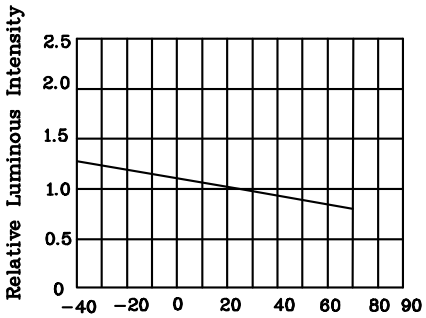
❖ **UR**



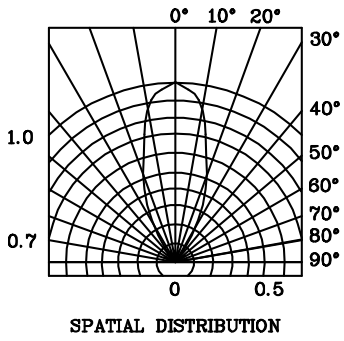
FORWARD VOLTAGE Vs.
FORWARD CURNENT



FORWARD VOLTAGE Vs.
LUMINOUS INTENSITY



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Remarks:
If special sorting is required (e.g. binning based on luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:
1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
Note: Accuracy may depend on the sorting parameters.

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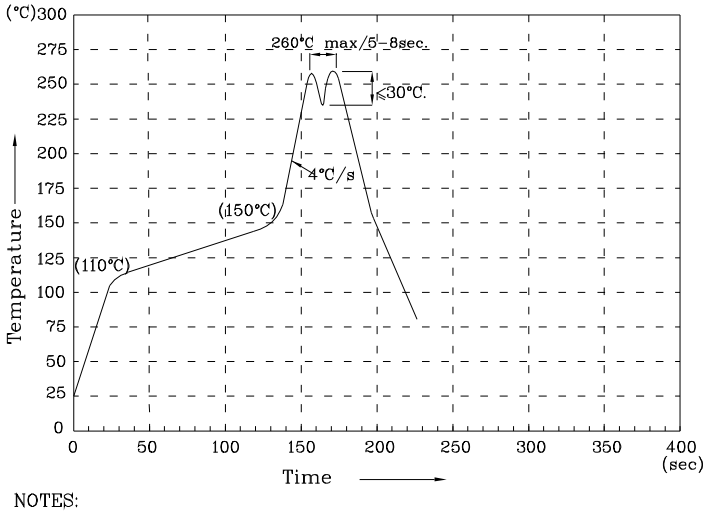
Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245℃~260℃.The maximum soldering temperature should be less than 260℃.
2. Do not apply stress on epoxy resins when temperature is over 85 degree℃.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.